

Product Change Notification / LIAL-25EAAM695

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28-Sep-2022

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5242 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 24LCxxx, 24AAxxx and 24FCxxx device families available in 5L SOT-23 package assembled at MMT assembly site.

Affected CPNs:

LIAL-25EAAM695_Affected_CPN_09282022.pdf LIAL-25EAAM695_Affected_CPN_09282022.csv

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 24LCxxx, 24AAxxx and 24FCxxx device families available in 5L SOT-23 package assembled at MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change		
	Microchip	Microchip		
Assembly Site	Technology	Technology		
Assembly Site	Thailand (Branch)	Thailand (Branch)		
	(MMT)	(MMT		
Wire Material	Au	CuPdAu		
Die Attach Material	8390A	8390A		
Molding Compound Material	G600V	G600V		
Lead-Frame Material	CDA194	CDA194		

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:November 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	September 2022			>	November 2022				2		
Workweek	3 6	3 7	3 8	3 9	4 0		4 5	4 6	4 7	4 8	4 9
Initial PCN Issue Date					Χ						
Qual Report Availability										Х	
Final PCN Issue										Х	

Date	
Method to Identify C	hange:Traceability code
Qualification Plan:Ple	ease open the attachments included with this PCN labeled as PCN_#_Qual_Plan.
Revision History:Sept	rember 28, 2022: Issued initial notification.
_	I in this PCN does not alter Microchip's current regulatory compliance regarding the ne applicable products.
Attachments:	
PCN_LIAL-25EAAN	1695_Qual Plan.pdf
Please contact your	local Microchip sales office with questions or concerns regarding this notification.
Terms and Condition	ins:
<mark>home page</mark> select re	ve Microchip PCNs via email please register for our PCN email service at our PCN egister then fill in the required fields. You will find instructions about registering for ail service in the PCN FAQ section.
	ge your PCN profile, including opt out, please go to the PCN home page select login nyMicrochip account. Select a profile option from the left navigation bar and make tions.

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Affected Catalog Part Numbers (CPN)

24LC08BT-I/OTRVE

24AA08T-I/OT

24AA08T-I/OTB22

24LC08BT-E/OT

24LC16BT-I/OT

24AA16T-I/OT

24LC16BT-E/OT

24AA01T-I/OT

24LC02BT-I/OT

24AA02T-I/OT

24LC02BT-E/OT

24LC04BT-I/OT

24LC04BT-I/OTRVE

24AA04T-I/OT

24LC04BT-E/OT

24LC08BT-I/OT

24LC08BHT-I/OT

24AA08HT-I/OT

24LC08BHT-E/OT

24AA16T-I/OT118

24LC16BT-I/OTGYR

24LC16BT-M/OT

24AA16T-E/OT

24LC16BHT-I/OT

24AA16HT-I/OT

24LC16BHT-E/OT

24LC32AT-I/OT

24AA32AT-I/OT

24LC32AT-E/OT

24LC32AFT-I/OT

24AA32AFT-I/OT

24LC32AFT-E/OT

24LC64T-I/OT

24AA64T-I/OT

24FC64T-I/OT

24LC64T-E/OT

24AA64T-E/OT

24LC64FT-I/OT

24AA64FT-I/OT

24FC64FT-I/OT

24LC64FT-E/OT

24AA04T-I/OT103

24LC04BHT-I/OT

24AA04HT-I/OT

24LC04BHT-E/OT

24LC01BT/OT

Date: Tuesday, September 27, 2022

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24LC01BT-I/OTA24

24LC01BT-E/OT

24AA02T-I/OT103

24LC01BHT-I/OT

24AA01HT-I/OT

24LC01BHT-E/OT

24LC02BHT-I/OT

24AA02HT-I/OT

24AA02E48T-I/OT

24AA02E64T-I/OT

24AA02UIDT-I/OT

24LC02BHT-E/OT

24AA02E48T-E/OT

24AA02E64T-E/OT

Date: Tuesday, September 27, 2022